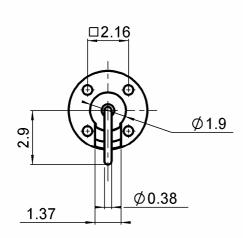
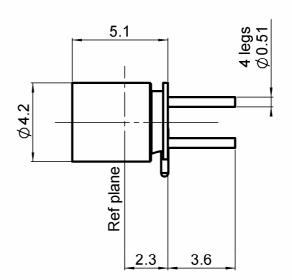
PIN IN PASTE - SMOOTH BORE

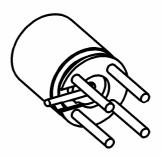
R222.428.700

Series: SMP









All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL + BRASS BERYLLIUM COPPER - PTFE -	PASSIVATED + GOLD 0.5 OVER NICKEL 2 GOLD 1.27 OVER NICKEL 1.27 -
-	-	-
-	-	-

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be



PIN IN PASTE - SMOOTH BORE

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PACKAGING

Standard Unit Other 100 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω **0-18** GHz

Frequency **VSWR**

1.15* + **0.0000** x F(GHz) Maxi Insertion loss **0.12** $\sqrt{F(GHz)}$ dB Maxi **NA** - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage 500 Veff mini Insulation resistance

RF leakage

5000 MΩ mini

ENVIRONMENTAL

-65/+165 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

Compliant with MIL-STD-348 *At 12.4GHz - Performance strongly depends on lay out and PCB material

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end **6.8** N mini **6.8** N mini Axial force – Opposite end Torque N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 1000 Cycles mini

Weight **0,3500** g

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SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

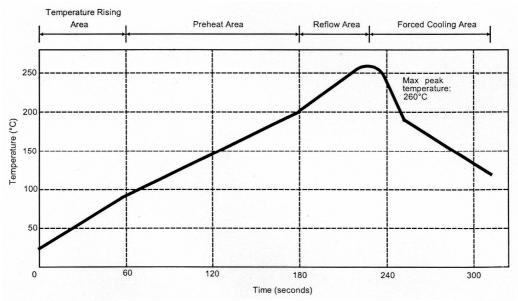
We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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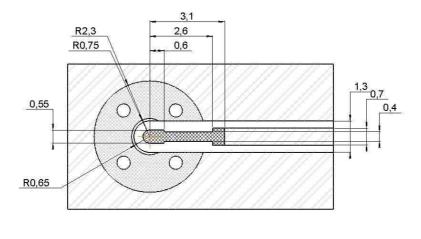
Series : SMP

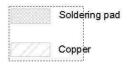
R222.428.700

PIN IN PASTE - SMOOTH BORE

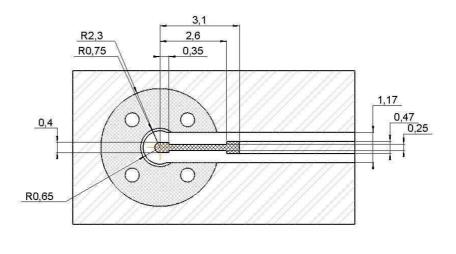
RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides : Add vias between both sides along upper ground plane according to engineering practise





Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise





Soldering pad

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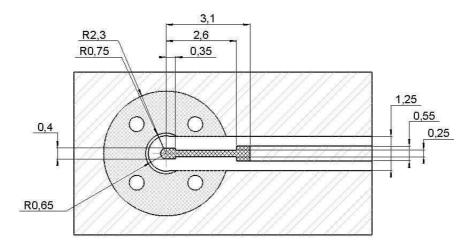


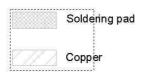
PIN IN PASTE - SMOOTH BORE

R222.428.700

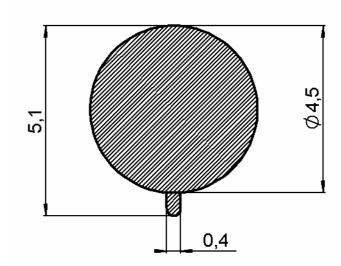
Series: SMP

Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise





SHADOW FOR VIDEO CAMERA



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